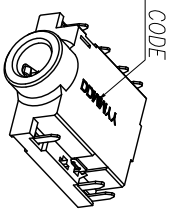
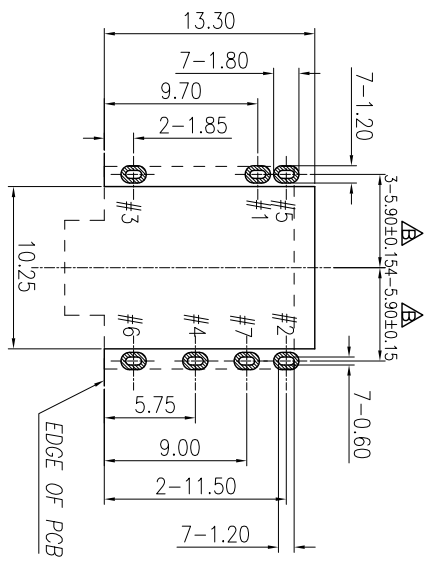
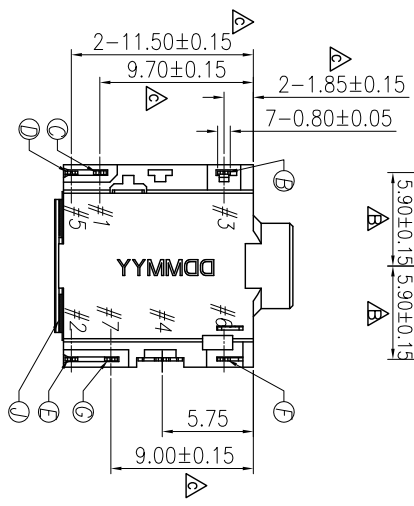
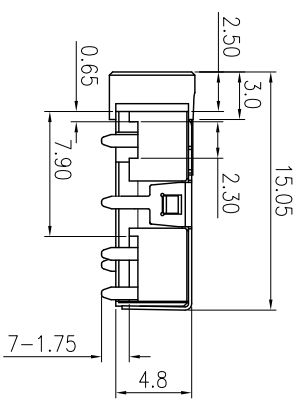
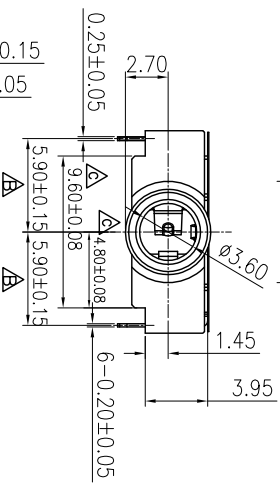
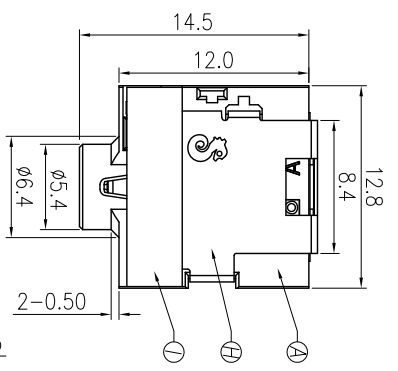


REV.	ECN NO.	OR DESCRIPTION	REVISED	DATE
A		PRODUCT RELEASE	ZLS	2013.01.02
B		ECN NO.: C130046 ADD. SIZE TOLERANCE	ZJK	2013.06.14
C		ECN NO.: C140239 MODIFY TOLERANCE	ZLS	2014.12.12

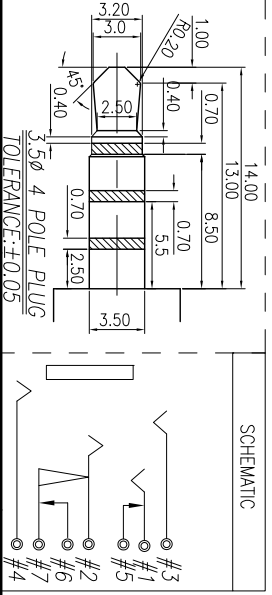


SPECIFICATIONS:

- ELECTRICAL CHARACTERISTICS:
 - RATING: 12V, 1A
 - CONTACT RESISTANCE: 50mΩ MAX.
 - DIELECTRIC WITHSTANDING VOLTAGE: 500V AC FOR ONE MINUTE.
 - INSULATION RESISTANCE: 100 MEGOHMS BY 500V DC
- MECHANICAL CHARACTERISTICS:
 - INSERTION FORCE: 0.4~3.0 KGf
 - WITHDRAWAL FORCE: 0.3~2.0 KGf
 - LIFE TEST: 5,000 CYCLES MIN.
 - OTHER GENERAL SPEC. TO REFER "2SJ2285 SERIES SPEC."
 - TO CONFORM TO THE SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
 - HALOGEN FREE PRODUCT IDENTIFICATION MARK ON JACK: ©
 - HALOGEN FREE PRODUCT IDENTIFICATION LABEL ON PACKAGING:
 - FOR REFLOW SOLDERING LEAD-FREE PROCESS.
 - PACKAGING: TAPE & REEL.



RECOMMENDED P.C.B. LAYOUT T=1.00
TOP VIEW (TOLERANCE: ±0.05)



SCHEMATIC

J	MYLAR	1	MYLAR 0.075T	YELLOW
I	MYLAR	1	MYLAR 0.075T	YELLOW
H	SHELL	1	COPPER ALLOY 0.20T	NI PLATING
G	TRANSFER TERMINAL	1	COPPER ALLOY 0.20T	Gold Flash on contact area and Solder Tullall over Nickel Plated
F	BREAK TERMINAL	1	COPPER ALLOY 0.20T	GOLD FLASH
E	RING	1	COPPER ALLOY 0.20T	Gold Flash on contact area and Solder Tullall over Nickel Plated
D	SHUNT	1	COPPER ALLOY 0.20T	GOLD FLASH
C	TIP	1	COPPER ALLOY 0.25T	Gold Flash on contact area and Solder Tullall over Nickel Plated
B	EARTH	1	COPPER ALLOY 0.20T	GOLD FLASH
A	BODY	1	HIGH TEMP THERMOPLASTIC UL 94V-0	BLACK COLOR
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR

UNLESS OTHERWISE SPECIFIED TOLERANCES
 Singatron Enterprise Co., Ltd.
 信音企業股份有限公司

DECIMALS:	ANGLES:	TITLE	3.5φ PHONE JACK
X : ±0.5	X : ±2°	DWN	215 14/12/23
X.X : ±0.3	X.X : ±1°	CHKD	BLLV 14/12/23
X.XX : ±0.2		APVD	SLZ 14/12/23

PART NO.	2SJ2284-005592F
SCALE	3:1
UNIT	mm
SHEET	10F1
REV.	C

CUSTOMER COPY